



SOT873-1

DFN3333-8: plastic thermal enhanced very thin small outline package; no leads; 8 terminals

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	DFN3333-8
Package type industry code	DFN3333-8
Package style descriptive code	HVSON (thermal enhanced very thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	19-4-2010

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		3.2	-	3.3	3.4	mm
E	package width		3.2	-	3.3	3.4	mm
A	seated height		[tbd]	-	[tbd]	1	mm
e	nominal pitch		-	-	0.65	-	mm
n ₂	actual quantity of termination		-	-	8	-	



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2. Package outline

DFN3333-8: plastic thermal enhanced very thin small outline package; no leads;
8 terminals; body 3.3 x 3.3 x 1.0 mm

SOT873-1

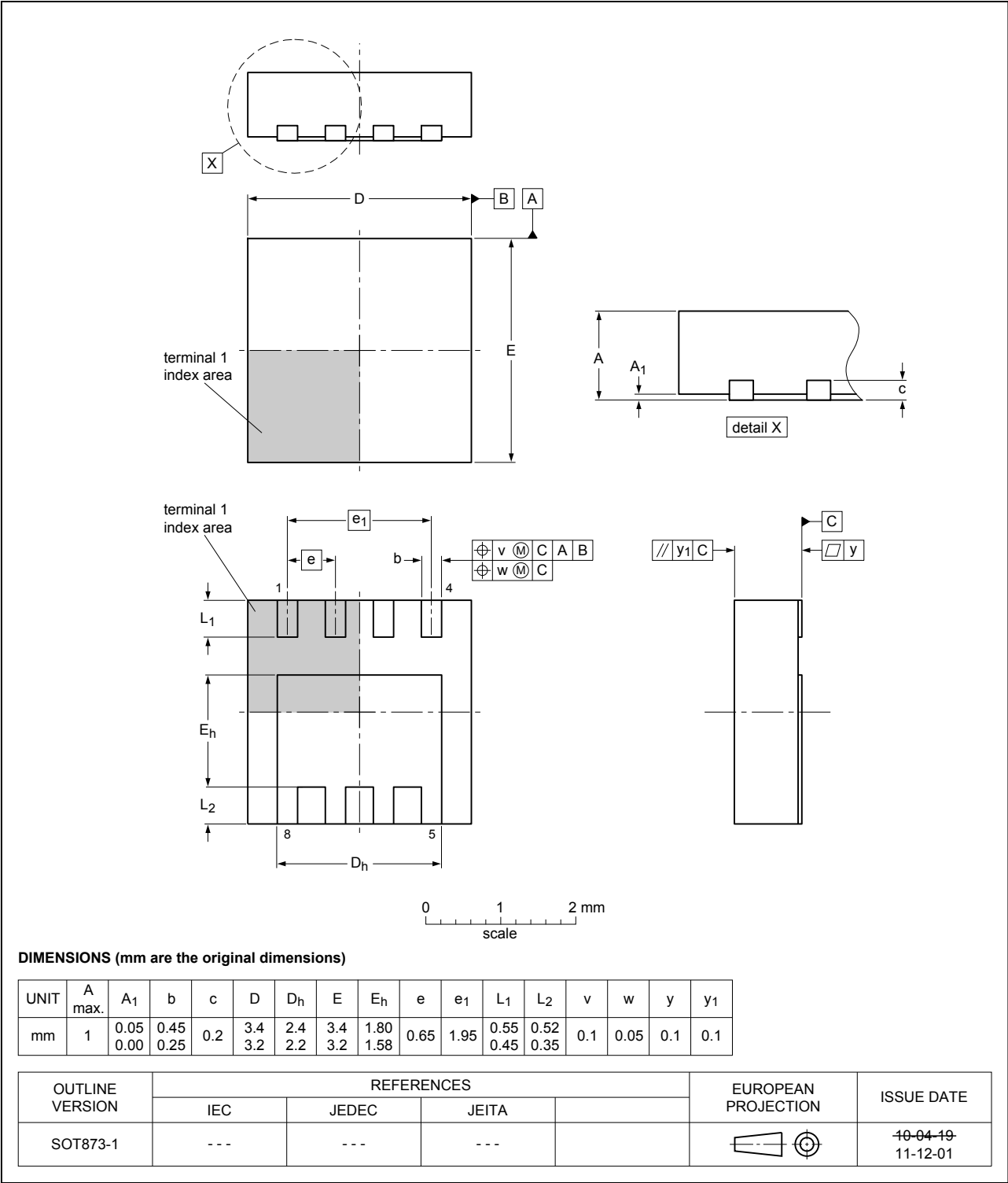


Fig. 1. Package outline DFN3333-8 (SOT873-1)

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3. Soldering

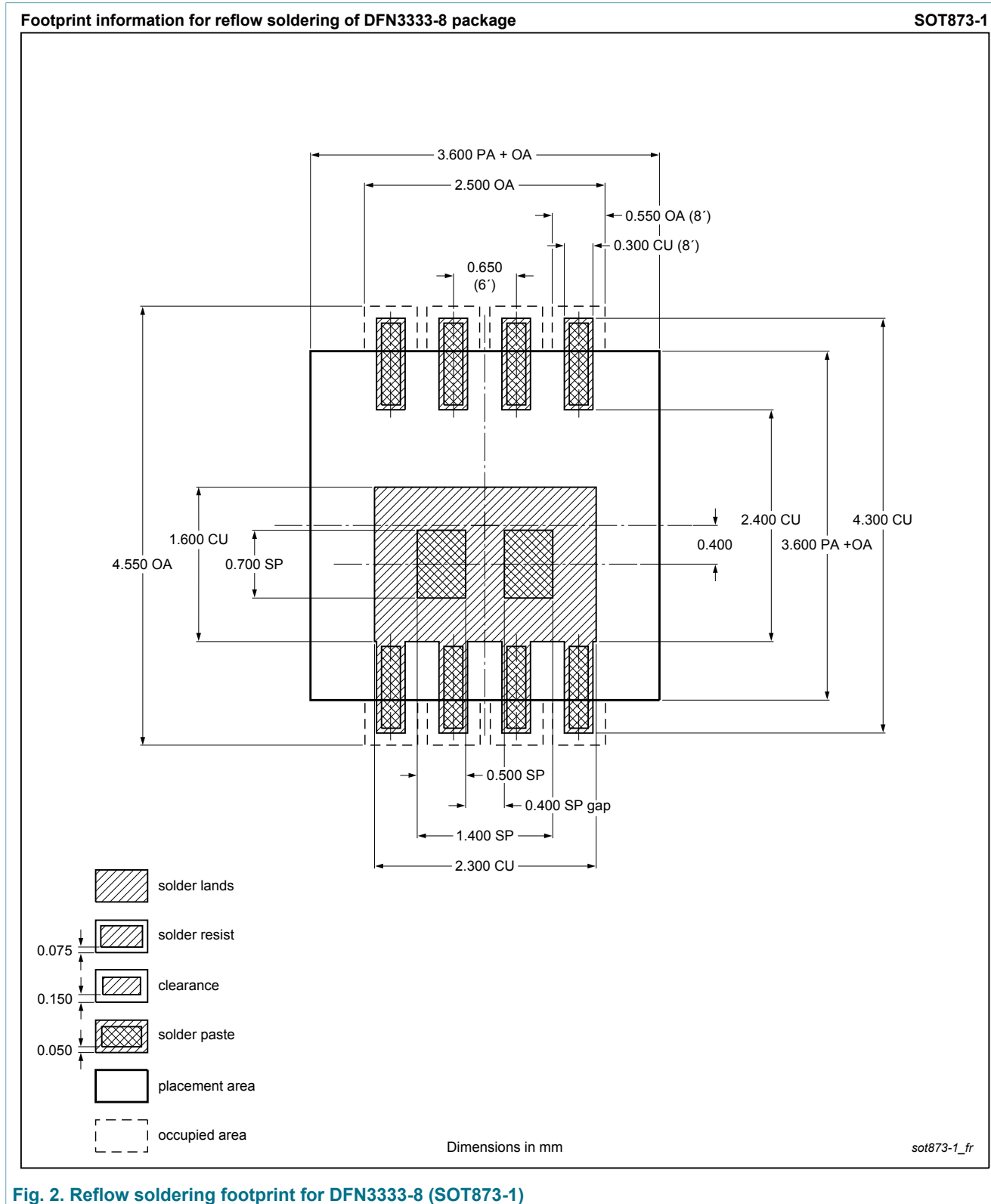


Fig. 2. Reflow soldering footprint for DFN3333-8 (SOT873-1)

4. Legal information

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DFN3333-8: plastic thermal enhanced very thin
small outline package; no leads; 8 terminals

5. Contents

1. Package summary..... 1

2. Package outline..... 2

3. Soldering..... 3

4. Legal information..... 4

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